14h00- 14h05  PACK4EU Final workshop - Opening by Jean-Marc YANNOU (ASE)- Auditorium

14h05- 14h30  “Semiconductor and packaging landscape in EU amidst a global geopolitical context”, Emilie Jolivet (Yole) and Stefan Chitoraga (Yole).
14h30-14h40:  “European Chips Act – First of a kind fabs, IPCEI and Chips4 EU initiative – but what about packaging?”, Elisabeth Steimetz (EPOSS, VDI-VDE).
14h40- 14h45: “The European INFRACHIP program”, Tony Maindron, (Minalogic).
14h45-14h50:  “The PEPR Électronique Packaging Concerted Action”, Hugues Granier ( LAAS-CNRS, University of Toulouse), David Henry (Univ. Grenoble Alpes, CEA).
14h50– 15h20: “Pack4EU project final recommendations”, Regis Hamelin, Pack4EU coordinator (Blumorpho)

15h40 – 16h00  Coffee break (Exhibition Hall) sponsored by PACK4EU

16h00 – 17h00  Pannel session- “Reactions to the PACK4EU Final recommendations”
Chairman, Renaud de LANGLADE (EPOSS and Chips JU, Board member) and Sanae BOULAY (IMAPS FR, NXP)
  ▪ Laurent Herard- ST
  ▪ Jean-René Lèquepeys- CEA
  ▪ Didier Floriot- Thales
  ▪ Mario Ibrahim- AT&S
  ▪ Fabien Corsat- ITEN
  ▪ Eric Fribourg-Blanc, Chips Joint Undertaking
  ▪ French PA, DGE tbc
  ▪ Regional PA: Rhones Alpes tbc.

17h00 – 17h50  Open discussion with the audience

17h50 – 18h00  Closing remarks by Jean-Marc YANNOU (ASE)

18h00 -19h15  PACK4EU Cocktail with Minapad exhibitors

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